

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1071276	flipchip (flip adj chip) bump ball bga	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/17 23:45
L2	228340	(support\$4 structure polymer\$4 epoxy resin) with 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/18 00:38
L3	5236	(encapsulat\$4 encase underfill\$4) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/17 23:47
L4	2255	(packag\$4 same 3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/17 23:48
L5	1767	(substrate carrier board pcb motherboard) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/18 00:38
L6	1767	(substrate carrier board pcb motherboard) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/18 00:38
L7	779	(polymer\$4) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/18 00:39